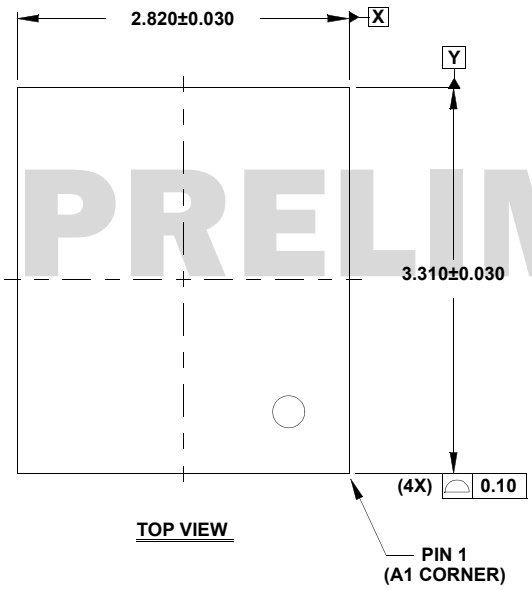
Package Outline Drawing

W7x8.46

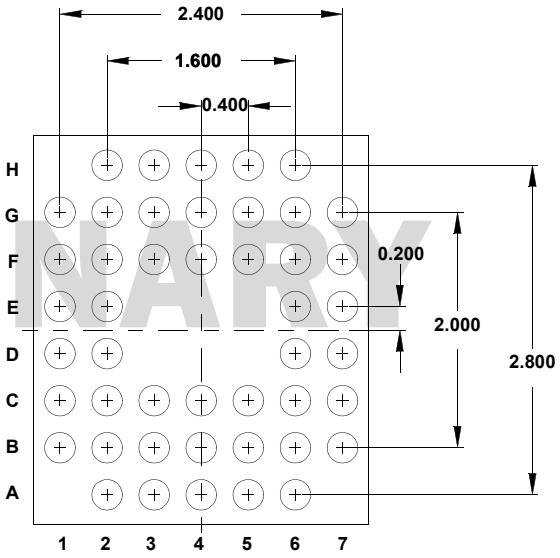
7X8 ARRAY 46 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE

Rev 0, 11/12

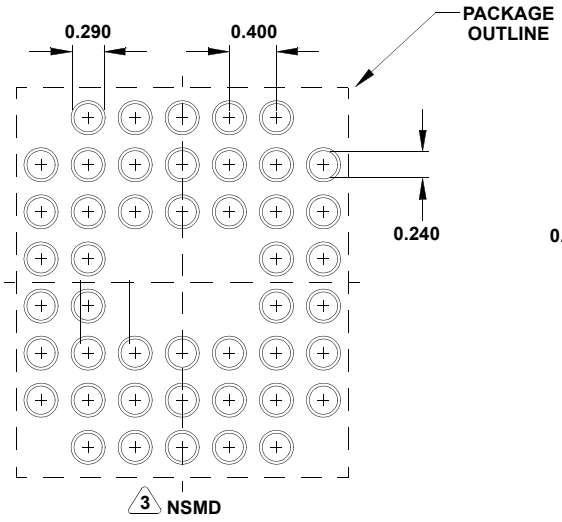
PRELIMINARY



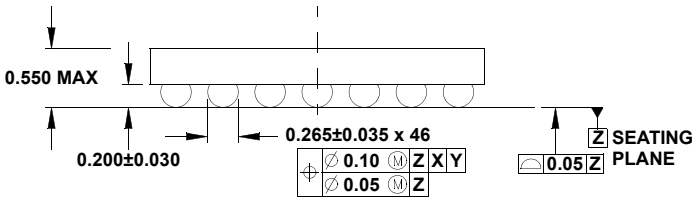
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance conform to ASMEY14.5-1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Technical Brief http://www.intersil.com/data/tb/tb451.pdf